

Product / Package Information

Package	LFCSP
Body Size (mm)	4 X 4 X 1.45
Lead Count	16
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes with exemption
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	3.46E-02	93.7	937000	53.38		533832
Thermosets	Epoxy resin	Proprietary	1.11E-03	3.0	30000	1.71		17092
Thermosets	Phenol resin	Proprietary	1.11E-03	3.0	30000	1.71		17092
Other inorganic materials	Carbon black	1333-86-4	1.11E-04	0.3	3000	0.17		1709
Subtotal			3.70E-02	100.00	1000000	56.97		569725

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	1.77 E-02	96.20	962000	27.31		273104
Copper & its alloys	Nickel	7440-02-0	5.53 E-04	3.00	30000	0.85		8517
Copper & its alloys	Silicon	7440-21-3	1.20 E-04	0.65	6500	0.18		1845
Copper & its alloys	Magnesium	7439-95-4	2.76 E-05	0.15	1500	0.04		423
Subtotal			1.84 E-02	100.00	1000000	28.39		283892

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	5.48 E-04	100.0	1000000	0.84		8444

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	2.50 E-04	100.0	1000000	0.39		3852

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	2.66 E-04	99.0	990000	0.41		4103
Precious metals	Palladium	7440-05-3	2.69 E-06	1.00	10000	0.004		41
Subtotal			2.69 E-04	100.0	1000000	0.41		4145

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	5.18 E-03	100.0	1000000	7.98		79767

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Thermoset	Resin	Proprietary	1.38 E-03	58	580000	2.12		21198
Other organic materials	Polytetrafluoroethylene	9002-84-0	9.96 E-04	42	420000	1.54		15350
Subtotal			2.37 E-03	100.0	1000000	3.65		36548

Seal Glass

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Ceramics/Glass	Lead borosilicate glass	65997-17-3	7.74 E-04	87.5	875000	1.19		11925
Ceramics/Glass	Aluminosilicate glass	65997-17-3	1.11 E-04	12.5	125000	0.17		1704
			8.85 E-04			1.36		13629

Package Totals			Weight (g) 6.49 E-02			Percentage (%) 100		PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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